

## Vishay General Semiconductor

# Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier



#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	2.0 A			
V <sub>RRM</sub>	60 V			
I <sub>FSM</sub>	50 A			
$V_F$ at $I_F = 1.0$ A $(T_J = 125  ^{\circ}C)$	0.42 V			
T <sub>J</sub> max.	175 °C			
Package	DFN3820A			
Circuit configuration	Single			

#### **FEATURES**

· Low profile package - typical height of 0.88 mm



- Trench MOS Schottky technology
- Low power losses, high efficiency
- Low forward voltage drop
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



- AEC-Q101 qualified available
  - Automotive ordering code; base P/NHM3
- Compatible to SMP (DO-220AA) package case outline
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

#### **TYPICAL APPLICATIONS**

For use in low voltage, high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

#### **MECHANICAL DATA**

Case: DFN3820A

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)				
PARAMETER	SYMBOL	V2NM63	UNIT	
Device marking code		2MF		
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	60	V	
Maximum average forward rectified current (fig. 1)	I <sub>F(AV)</sub> (1)	2	А	
Maximum average forward rectified current (fig. 1)	I <sub>F(AV)</sub> (2)	1.9	А	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	50	А	
Operating junction temperature range	T <sub>J</sub> <sup>(3)</sup>	-40 to +175	°C	
Storage temperature range	T <sub>STG</sub>	-55 to +175	°C	

#### **Notes**

- (1) Mounted on 10 mm x 10 mm copper pad area PCB
- (2) Free air, mounted on FR4 PCB, 2 oz., standard footprint
- $^{(3)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$



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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CO	ONDITIONS	SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.0 A	— T₁= 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.51	-	V
	I <sub>F</sub> = 2.0 A			0.58	0.63	
	I <sub>F</sub> = 1.0 A	T <sub>J</sub> = 125 °C		0.42	-	
	I <sub>F</sub> = 2.0 A			0.51	0.56	
Reverse current	V <sub>R</sub> = 60 V	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	0.01	mΛ
	v <sub>R</sub> = 60 v	T <sub>J</sub> = 125 °C		0.2	1.0	- mA
Typical junction capacitance	4.0 V, 1 MF	4.0 V, 1 MHz		350	-	pF

#### Notes

 $^{(1)}\,$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

(2) Pulse test: pulse width  $\leq 5$  ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise specified)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Thermal resistance	R <sub>0JA</sub> (1)(2)	140	175	°C/W
Thermal resistance	R <sub>0JM</sub> (3)	6	7.5	

#### Notes

 $^{(1)}$  The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ 

(2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

(3) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
V2NM63-M3/H	0.023	Н	3500	7" diameter plastic tape and reel	
V2NM63-M3/I	0.023	I	14 000	13" diameter plastic tape and reel	
V2NM63HM3/H (1)	0.023	Н	3500	7" diameter plastic tape and reel	
V2NM63HM3/I (1)	0.023	I	14 000	13" diameter plastic tape and reel	

#### Note

(1) AEC-Q101 qualified

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## **RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25$ °C unless otherwise noted)

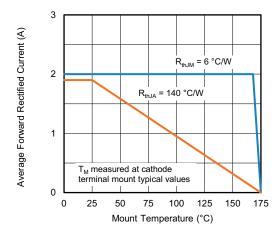


Fig. 1 - Maximum Forward Current Derating Curve

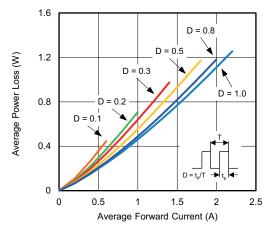


Fig. 2 - Forward Power Loss Characteristics

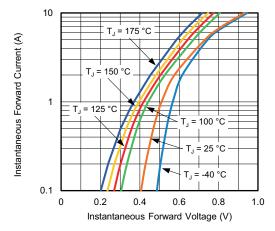


Fig. 3 - Typical Instantaneous Forward Characteristics

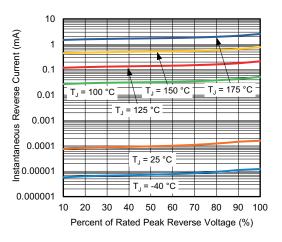


Fig. 4 - Typical Reverse Characteristics

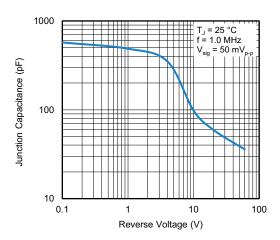


Fig. 5 - Typical Junction Capacitance

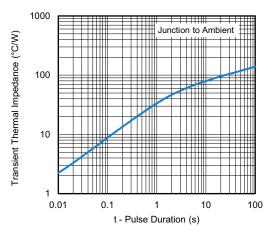


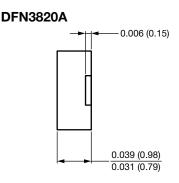
Fig. 6 - Typical Transient Thermal Impedance

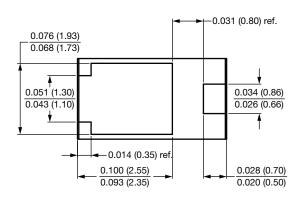


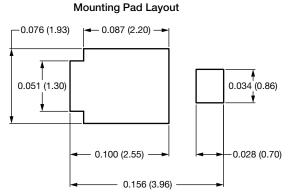
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### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

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